



Final Product Change Notification

201509014F01

Issue Date: 30-Nov-2015
Effective Date: 13-Mar-2016

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QUALITY

Management Summary

Release of Assembly Plant Guangdong (APG), China, as second source for product types in SOT323 package

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

APG as 2nd source assembly for product types in SOT323 package

Details of this Change

Release of NXP Assembly Plant Guangdong (APG), China, as second source of assembly and final test in addition to current location NXP Assembly Plant Seremban (APM), Malaysia, for dedicated product types in SOT323 package.

The existing processes from APM are copied exactly at APG. Both locations will operate under the same conditions, with same equipment and processes, at equal performance and with comparable systems.

The design and materials of all components will remain unchanged, i.e. no change of die, die attach, wire, mold compound, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

The implementation of this second source will increase production capacity and flexibility to ensure fulfillment of customer demands.

Identification of Affected Products

Products from APM are identified by vendor code "t" on package surface.

Products from APG will be identified by vendor code "W" on package surface.

Location is also stated on packing labels.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 31-Dec-2015.

Production

Planned first shipment 15-Mar-2016

Impact

No impact to the products' functionality anticipated. There is no change of operating processes and conditions, product design or materials.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Not applicable

Related Notifications

Notification Issue Date	Effective Date	Title
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201509014A25-Sep-2015		APG as 2nd source assembly for product types in SOT323 package
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Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 30-Dec-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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